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PATENT

CJ.

7/23/01

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Date

3/26/01

Nicole Bailey

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Robert A. Weaver, Gregory J. Wilson and Paul R. McHugh  
Application No. : 09/733,608  
Filed : December 8, 2000  
For : METHOD AND APPARATUS FOR PROCESSING A  
MICROELECTRONIC WORKPIECE AT AN ELEVATED  
TEMPERATURE

Art Unit : 1742  
Docket No. : 291958124US  
Date : March 26, 2001

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, DC 20231

PRELIMINARY AMENDMENT

Sir:

Please amend the application as follows:

In the Claims:

1 76. The method of claim 58 wherein thermally processing the selected  
2 material includes thermally annealing a copper layer electrochemically-deposited on the  
3 microelectronic workpiece.